



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-10-23
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32WB05KZV6TR	F042*FL06BD9	A	P1C7	2024-10-23
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	75	mg	Each	ECOPACK® 3

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	5x5	32	Flat	
Comment	Package : 42 VFQFPN 5X5x1.0 32L PITCH 0.5 7376875			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	F042*FL06BD9		74.5310		6000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	5.190	mg	supplier	die	Silicon (Si)	7440-21-3		4.921	mg	948119	66027.52616				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.013	mg	2496	173.8228063				
				supplier	metallization	Copper (Cu)	7440-50-8		0.114	mg	21929	1527.147564				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.037	mg	7131	496.6067435				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	357	24.86167542				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	178	12.39601744				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.029	mg	5527	384.9033055				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.074	mg	14263	993.2831276				
				Leadframe (C194)	Copper & its alloys	35.083	mg	supplier	Leadframe	Copper (Cu)	7440-50-8		34.304	mg	977802	460264.5532
								supplier	Leadframe	Iron (Fe)	7439-89-6		0.743	mg	21170	9965.003744
supplier	Leadframe	Zinc (Zn)	7440-66-6						0.034	mg	961	452.3556258				
supplier	Leadframe	Phosphorus (P)	7723-14-0						0.002	mg	67	31.53780117				
supplier	Glue or tape	Silver (Ag)	7440-22-4						0.505	mg	800000	6779.773478				
Glue epoxy (QMI-519)	Precious metals	0.632	mg	supplier	Glue or tape	Methylene diacrylate polymer	42594-17-2		0.104	mg	164000	1389.853563				
				supplier	Glue or tape	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.016	mg	25000	211.8679212				
				supplier	Glue or tape	Epoxyhexyloxyethyltrimethoxysilane	3388-04-3		0.003	mg	5000	42.37358423				
				supplier	SVHC	Bis(alpha,dimethylbenzyl) peroxide	80-43-3		0.003	mg	5000	42.37358423				
				supplier	Glue or tape	Palladium (Pd)	7440-05-3		0.001	mg	1000	8.474716847				
				supplier	Bonding wire	Copper (Cu)	7440-50-8		0.281	mg	990000	3775.794578				
Bonding wire (CuA)	Precious metals	0.284	mg	supplier	Bonding wire	Silver (Ag)	7440-22-4		0.001	mg	2000	7.627867835				
				supplier	Bonding wire	Other	Proprietary		0.002	mg	8000	30.51147134				
				supplier	Molding Compound	Silica vitreous	60676-86-0		29.081	mg	880000	390186.7994				
Encapsulation (CEL 9240ZHF10W)	M-011 Other inorganic materials	33.047	mg	supplier	Molding Compound	Biphenyl epoxy resin	85954-11-6		1.652	mg	50000	22169.70451				
				supplier	Molding Compound	Phenolic resin	205830-20-2		1.289	mg	39000	17292.36952				
				supplier	Molding Compound	Epoxy type resin A	Proprietary		0.661	mg	20000	8867.881805				
				supplier	Molding Compound	Epoxy type resin B	Proprietary		0.297	mg	9000	3990.546812				
				supplier	Molding Compound	Carbon black	1333-86-4		0.066	mg	2000	886.7881805				
				supplier	Plating	Nickel (Ni)	7440-02-0		0.271	mg	918364	3639.716438				
External Plating (Ni/Pd/Au)	M-011 Other inorganic materials	0.295	mg	supplier	Plating	Palladium (Pd)	7440-05-3		0.021	mg	69875	276.9328786				
				supplier	Plating	Gold (Au)	7440-57-5		0.003	mg	11761	46.61191535				